

Design Materials procurement Manufacturing

Exicom offers an advanced Circuit Design & Build Service that includes.

- Analogue and digital based designs
- Printed Circuit Board Layout
- Prototyping and testing
- Compliance Certifications
- Low, medium and high volume production.

Exicom has developed significant buying power and has negotiated favourable procurement contracts to reduce customer production costs.

- National as well as international contacts
- Inventory control
- Customs clearance requirements
- Electronic Components as well as mechanical hardware.



Surface Mount

The majority of current designs utilize the advantages of surface mount technologies. Exicom offers advanced surface mount placement equipment employing high precision laser optics for consistent quality at high speeds and reduced lead times.

- *Process:* Automated solder paste screen-print with image feedback, automated laser guided image feedback Yamaha YVL88 SMD placement, automated double side glue SMD placement, Multi-zone Heller 1500 reflow oven.
- *Components:* Rectangular chips 0402 and larger (resistors, capacitors, inductors), SOT packages, SOICs, QFPs down to 0.5 mm lead pitch. Supplied in plastic or paper tape, commonly 8 & 12 mm, or grid trays (Other tape sizes are possible)
- *Orientation:* Any angle

Automatic Insertion of through hole components

Our automated process offers fast and accurate placement of through hole components providing a cost effective assembly option.

- *Axials:* Resistors, diodes, inductors etc.
Lead dia: Up to 0.80 mm
Metric and Imperial pitched parts can be inserted.
- *Radials:* Electrolytics, plastic films, disc ceramics, transistors, LED's, etc.
Lead dia: Up to 0.6 mm
Metric lead pitches – 2.5, 5.0, 7.5 mm (2 x 2 in-line for Transistors).
Imperial pitch PCB's possible in some cases.
- *Orientation:* 0°, 90°, 180° & 270°
- *Lead Clinch:* Clinched inwards or outwards



Services

Hand Assembly

- Highly flexible facilities to make, pre-form, and manually insert components of all descriptions.
- EPROM and microcontroller programming
- Wire and coaxial preparation



Wave Soldering

The Exicom Dual Wave Soldering Process delivers high quality joints using pre-heating and spray fluxing techniques, which are essential for high volume manufacture.

- Using up to the minute machines for the best possible process.
- Using Low Solids, No-residue flux.
- Gives excellent results on multi-layer PCB's.



Testing

Exicom has comprehensive in-house testing facilities to ensure customer's products meet or exceed the standards specified.

- 25m³ environmental chamber available (-30°C to +60°C)
- Full range of calibrated instrumentation.
- Automatic testing available.
- Specialist in PCB repairs if required.
- Extensive range of RF test equipment



Packing & Shipping

Exicom can manage customer's logistics and ship products manufactured nationally or internationally, removing both the expense and delays caused through double handling.

- Product can be shipped direct to national or international customers if required.
- Jigs and fixtures for special requirements can be made in our workshop.

Warranty

- A full warranty repair and / or replacement service can be provided for products manufactured and tested by Exicom.

